



Aim High HPC @ Intel

CAS2K7 Workshop
September 10, 2007

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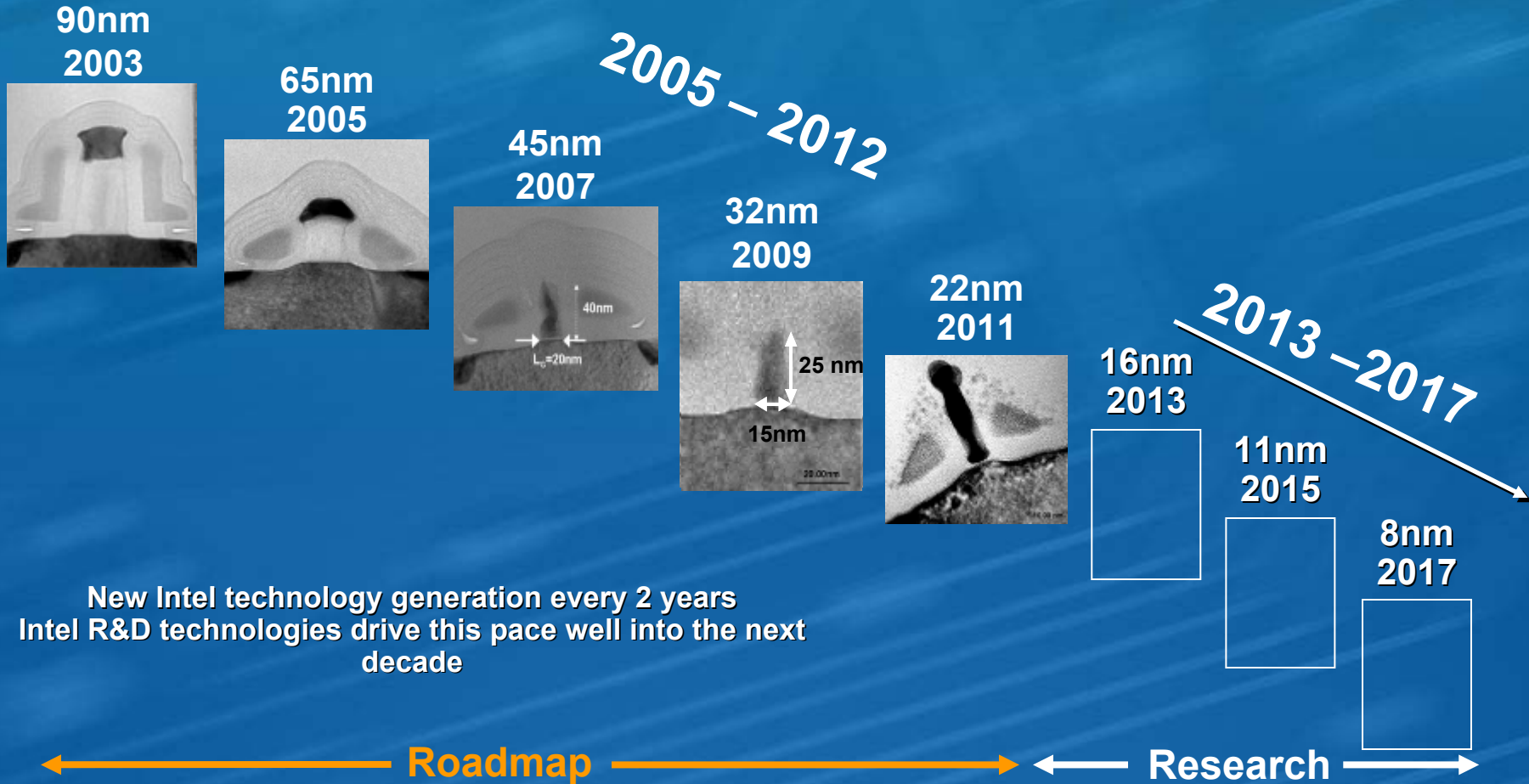
Risk Factors

Today's presentations contain forward-looking statements. All statements made that are not historical facts are subject to a number of risks and uncertainties, and actual results may differ materially. Please refer to our most recent Earnings Release and our most recent Form 10-Q or 10-K filing available on our website for more information on the risk factors that could cause actual results to differ.

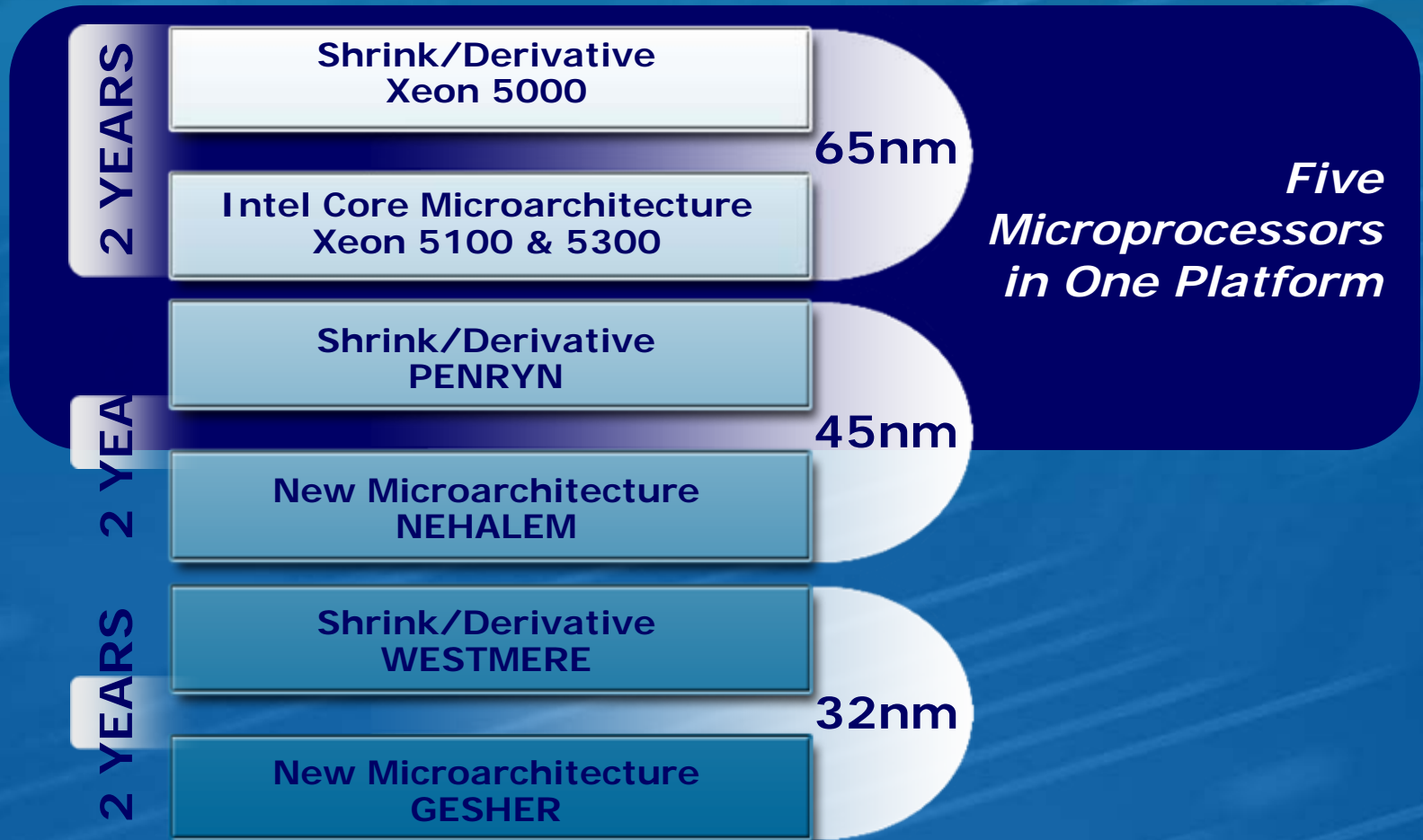
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Silicon Future

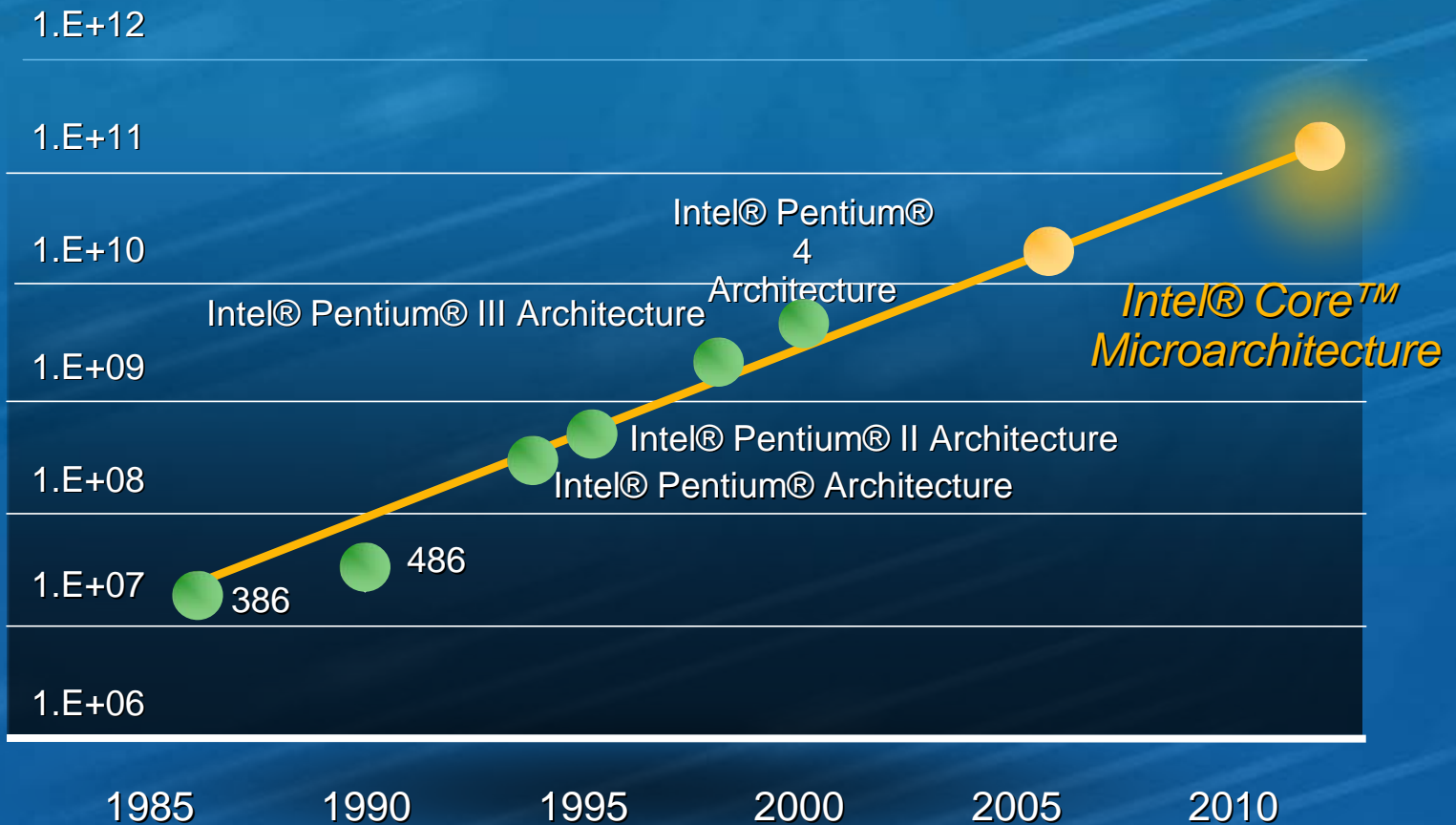


Intel Design & Process Cadence



Processor Performance

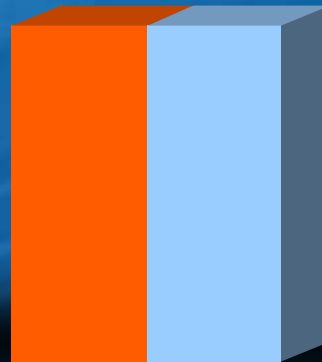
Flops



Why Multi-Core?

■ *Performance*
■ *Power*

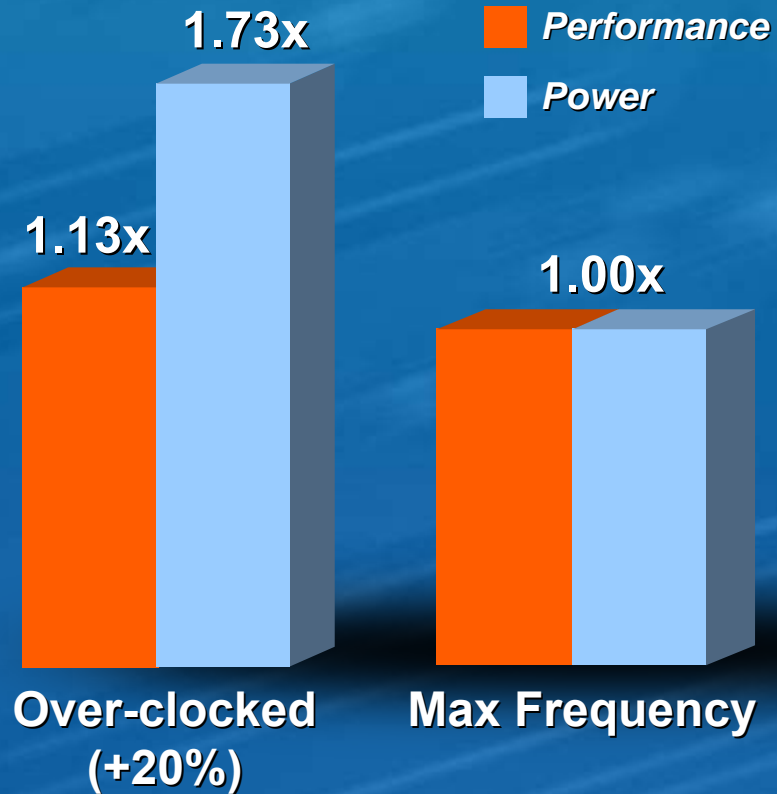
1.00x



Max Frequency

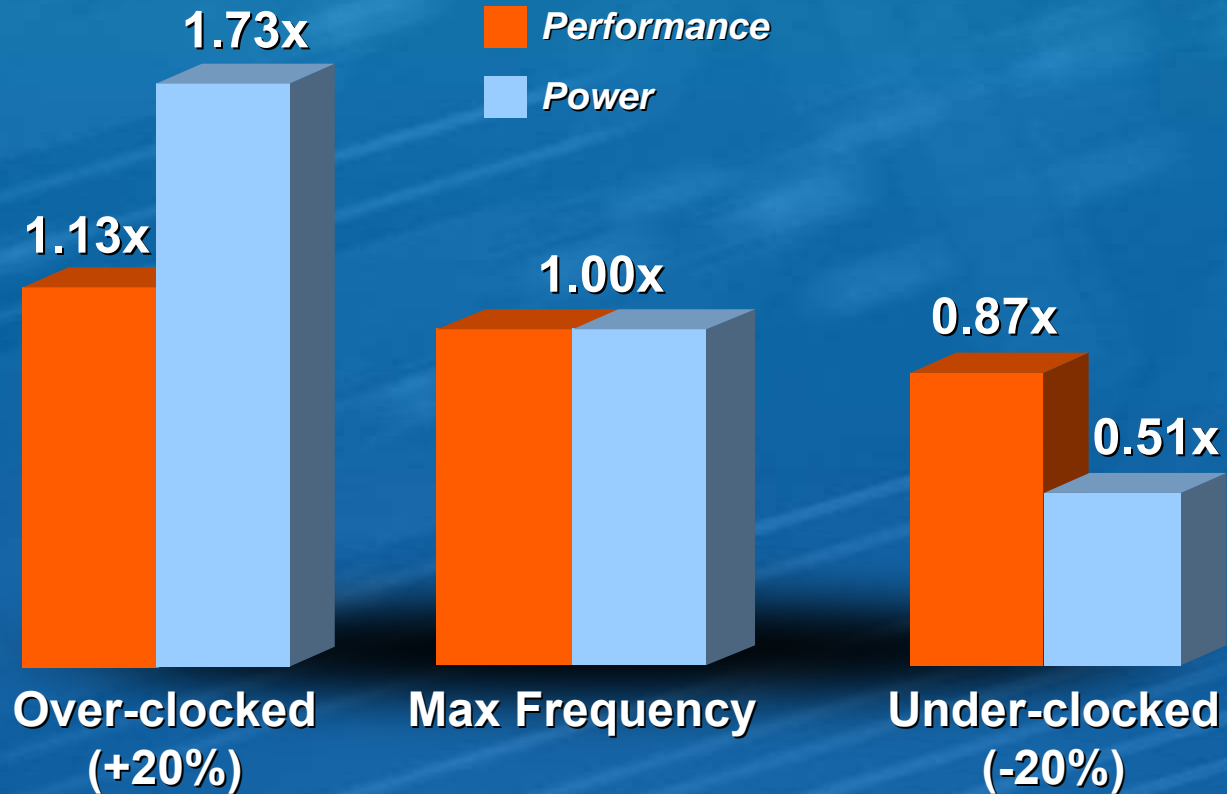
Relative single-core frequency and Vcc

Over-clocking



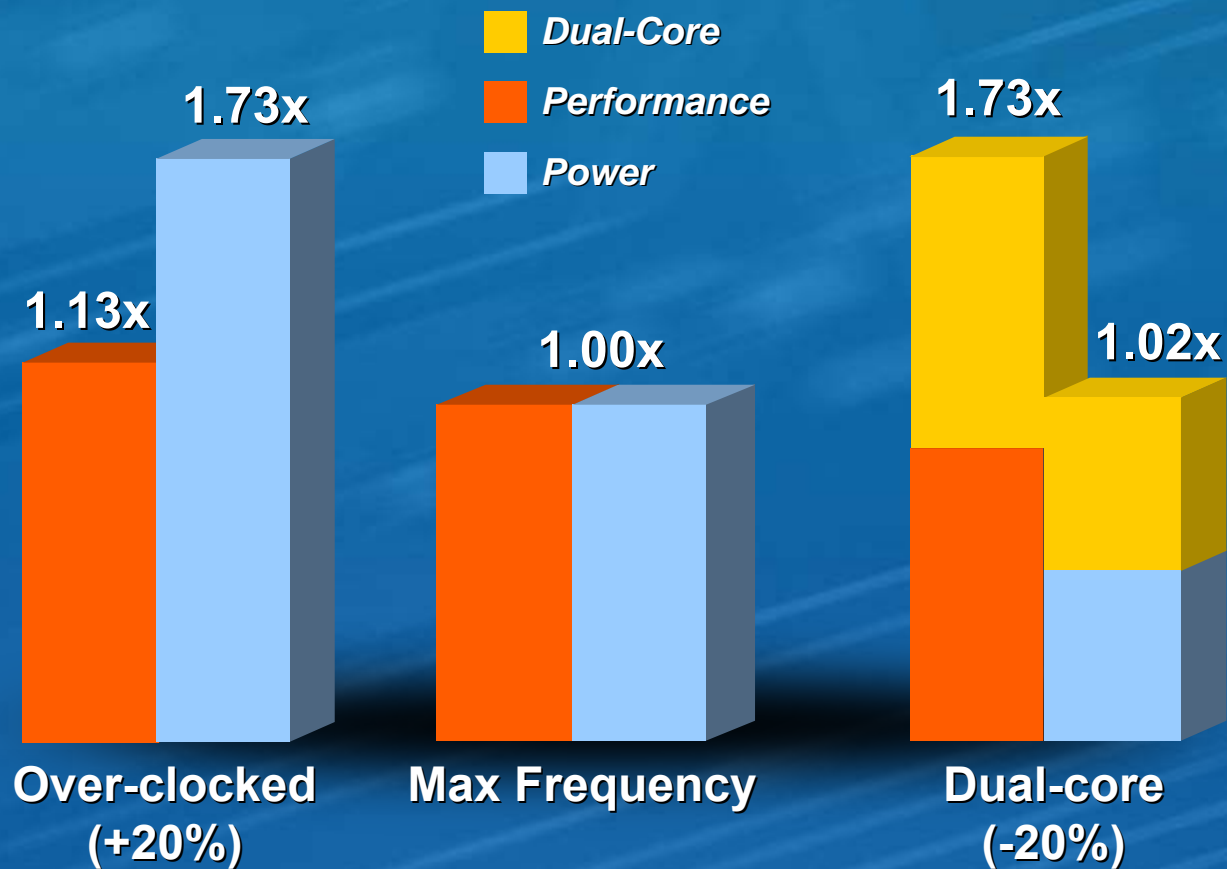
Relative single-core frequency and Vcc

Under-clocking



Relative single-core frequency and Vcc

Multi-Core Energy-Efficient Performance



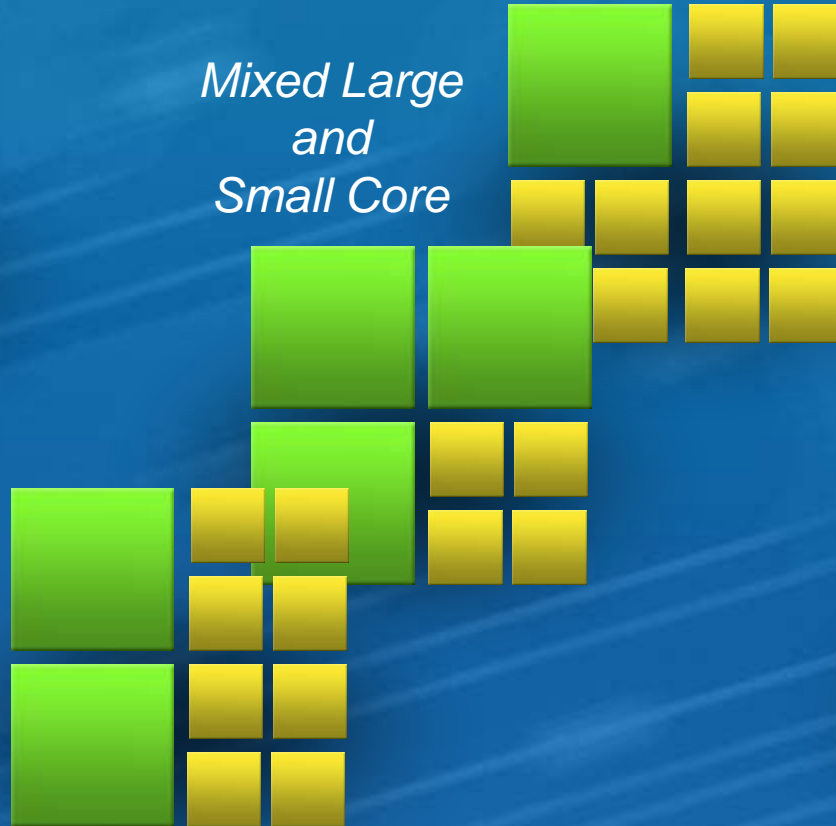
Relative single-core frequency and Vcc

Multi-threaded Cores

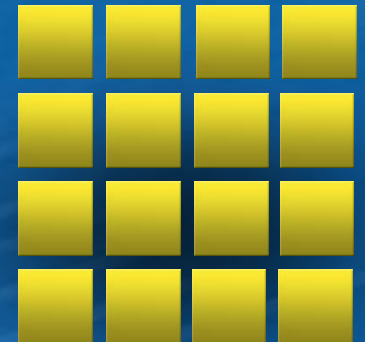
All Large Core



*Mixed Large
and
Small Core*



All Small Core



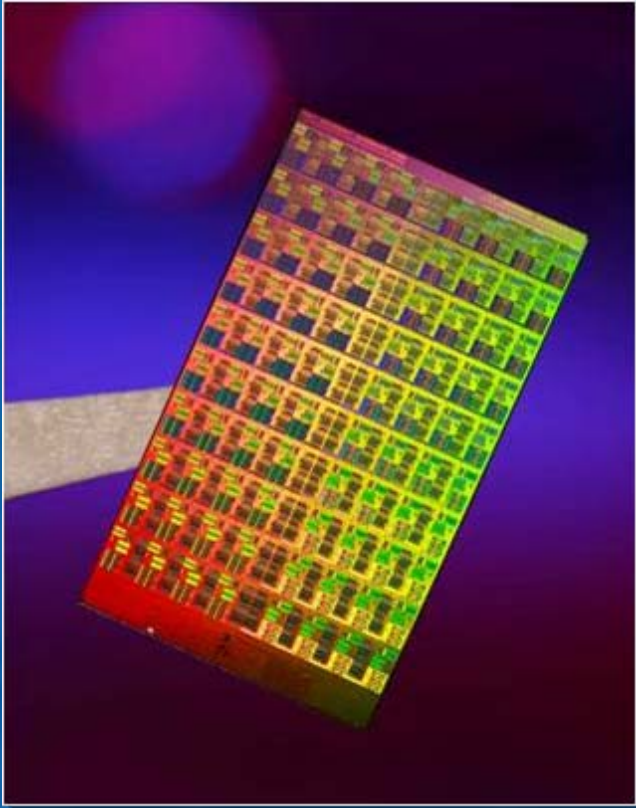
Goal: Energy Efficient Petascale with Multi-threaded Cores

Note: the above pictures don't represent any current or future Intel products



Teraflops Research Chip

100 Million Transistors • 80 Tiles • 275mm²



First tera-scale programmable silicon:

- Teraflops performance
- Tile design approach
- On-die mesh network
- Novel clocking
- Power-aware capability
- Supports 3D-memory

Not designed for IA or product

Tera-scale Introduction

- Represents significant Intel transition from “large” cores to 32+ low-power, highly-threaded IA cores per die
- Motivations for a new architecture
 - Enable emerging workloads and new use-models
 - Low Power IA cores provide 4-5X greater performance-power efficiency
 - Scaling beyond the limits of Instruction level parallelism and single-core power
- Tera-scale is *NOT* simply SMP-on-die
 - Will require complete platform and software enabling

Parameter	SMP	Tera-scale	Improvement	Optimizations
Bandwidth	12 GB/s	~1.2 TB/s	~100X	Massive bandwidth between cores
Latency	400 cycles	20 cycles	~20X	Ultra-fast synchronization



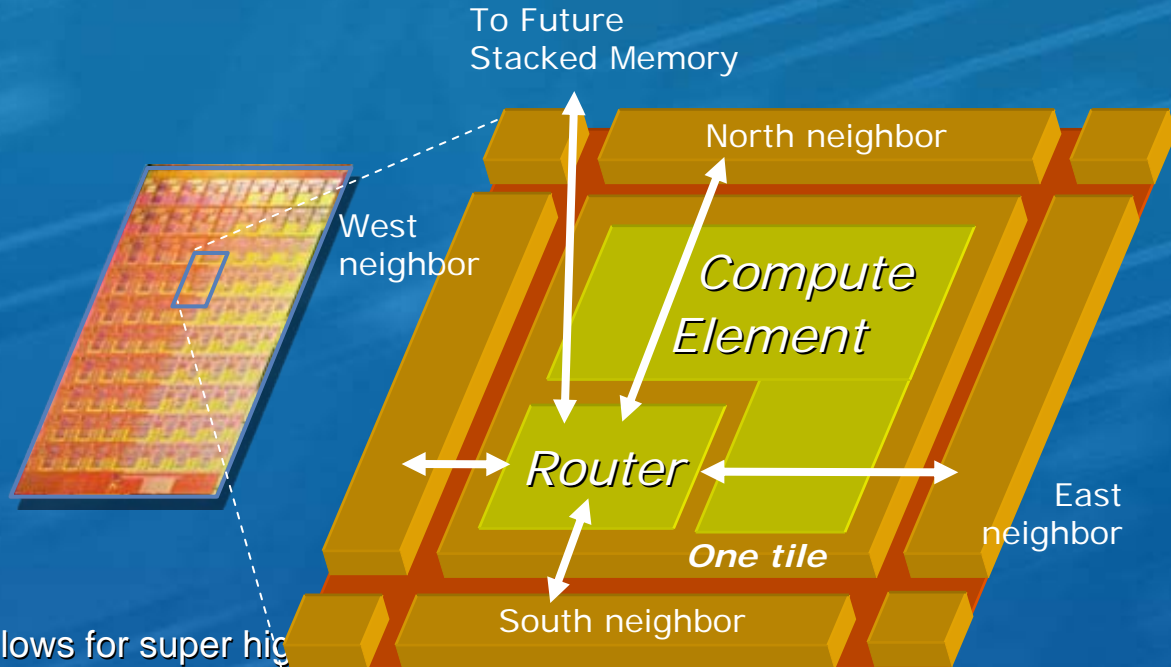
Tiled Design & Mesh Network

Repeated Tile Method:

- Compute + router
- Modular, scalable
- Small design teams
- Short design cycle

Mesh Interconnect:

- “Network-on-a-Chip”
 - Cores networked in a grid allows for super high communications in and between cores
- 5-port, 80GB/s* routers
- Low latency (1.25ns*)
- Future: connect IA/or and special purpose cores



* When operating at a nominal speed of 4GHz

Fine Grain Power Management

- Novel, modular clocking scheme saves power over global clock
- New instructions to make any core sleep or wake as apps demand
- Chip Voltage & freq. control (0.7-1.3V, 0-5.8GHz)

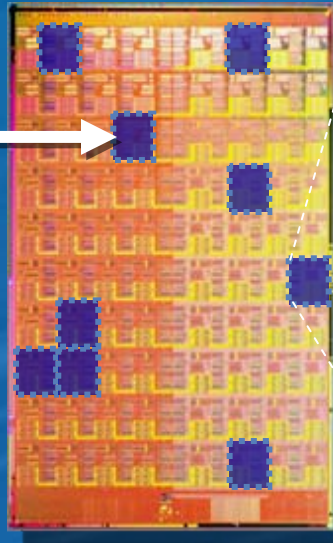
Dynamic sleep

STANDBY:

- Memory retains data
- **50%** less power/tile

FULL SLEEP:

- Memories fully off
- **80%** less power/tile



21 sleep regions per tile (not all shown)

Data Memory

Sleeping:
57% less power

Instruction Memory

Sleeping:
56% less power

Router

Sleeping:
10% less power
(stays on to pass traffic)

FP Engine 1

Sleeping:
90% less power

FP Engine 2

Sleeping:
90% less power

Industry leading energy-efficiency of 16 Gigaflops/Watt



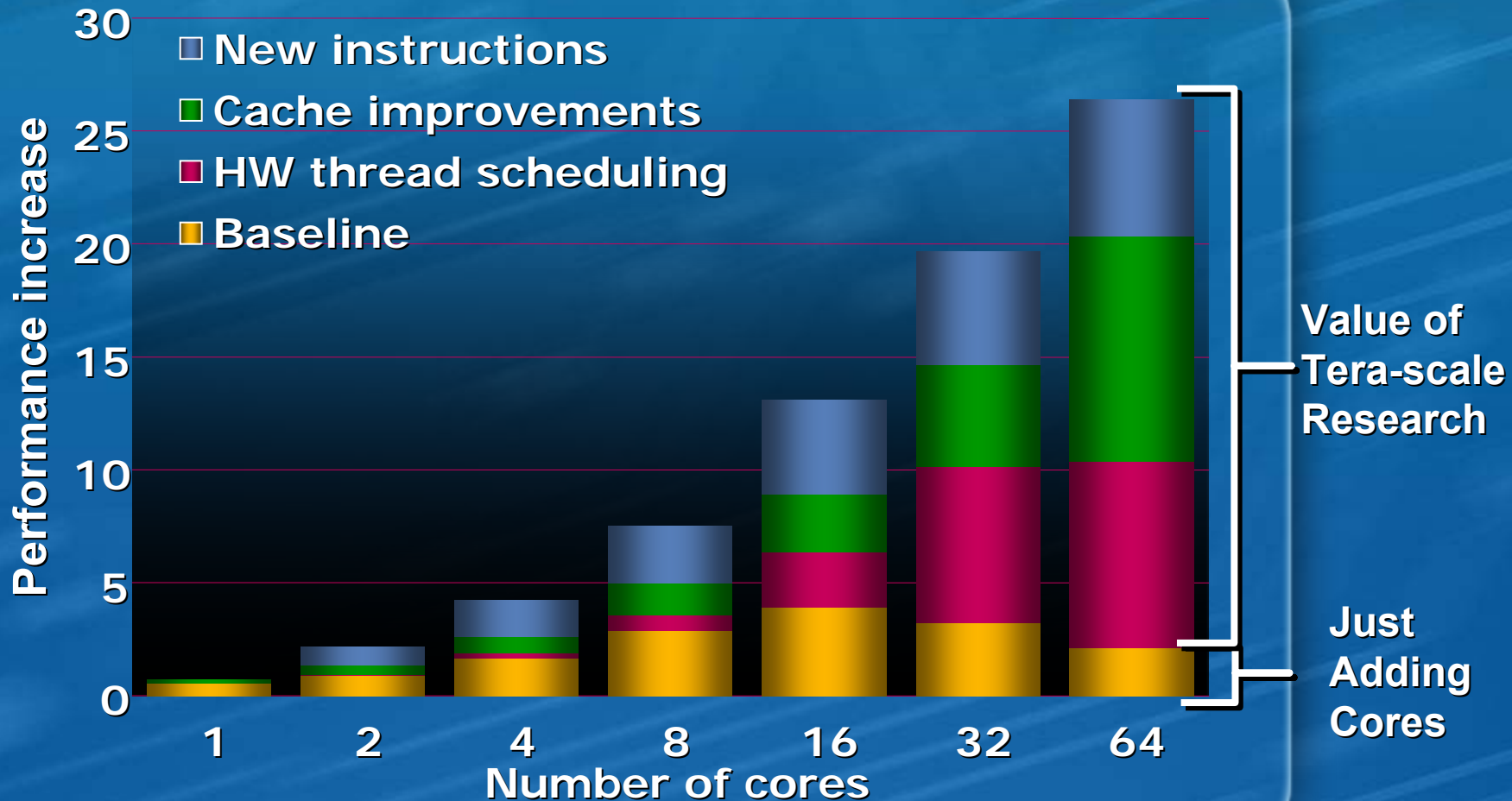
Research Data Summary

Frequency	Voltage	Power	Bisection Bandwidth	Performance
3.16 GHz	0.95 V	62W	1.62 Terabits/s	1.01 Teraflops
5.1 GHz	1.2 V	175W	2.61 Terabits/s	1.63 Teraflops
5.7 GHz	1.35 V	265W	2.92 Terabits/s	1.81 Teraflops

**1.01 Teraflops
62 Watts**

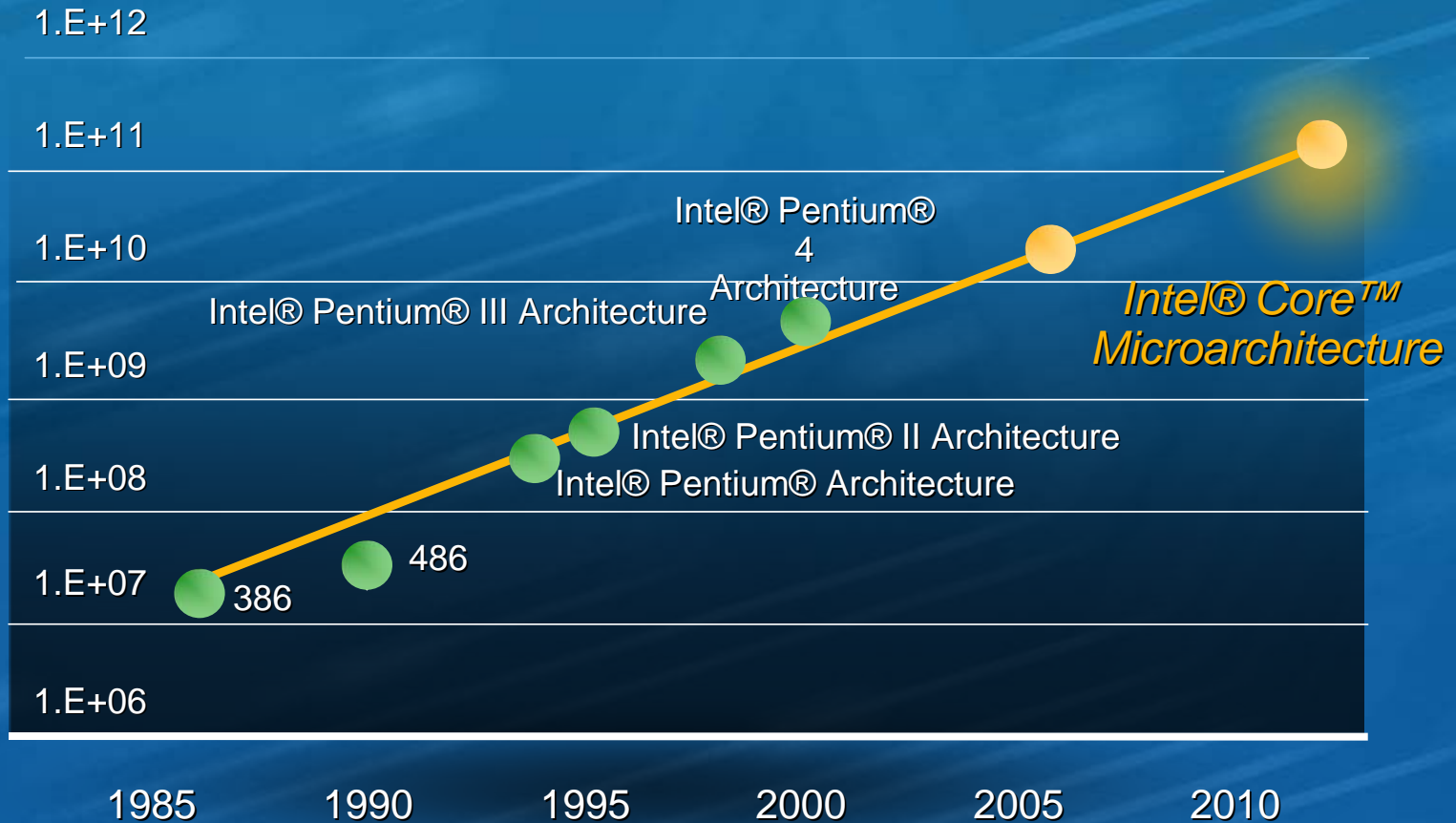


More than the Cores



Processor Performance

Flops



*Reaching Petascale with ~10,000 Processors in 2010**

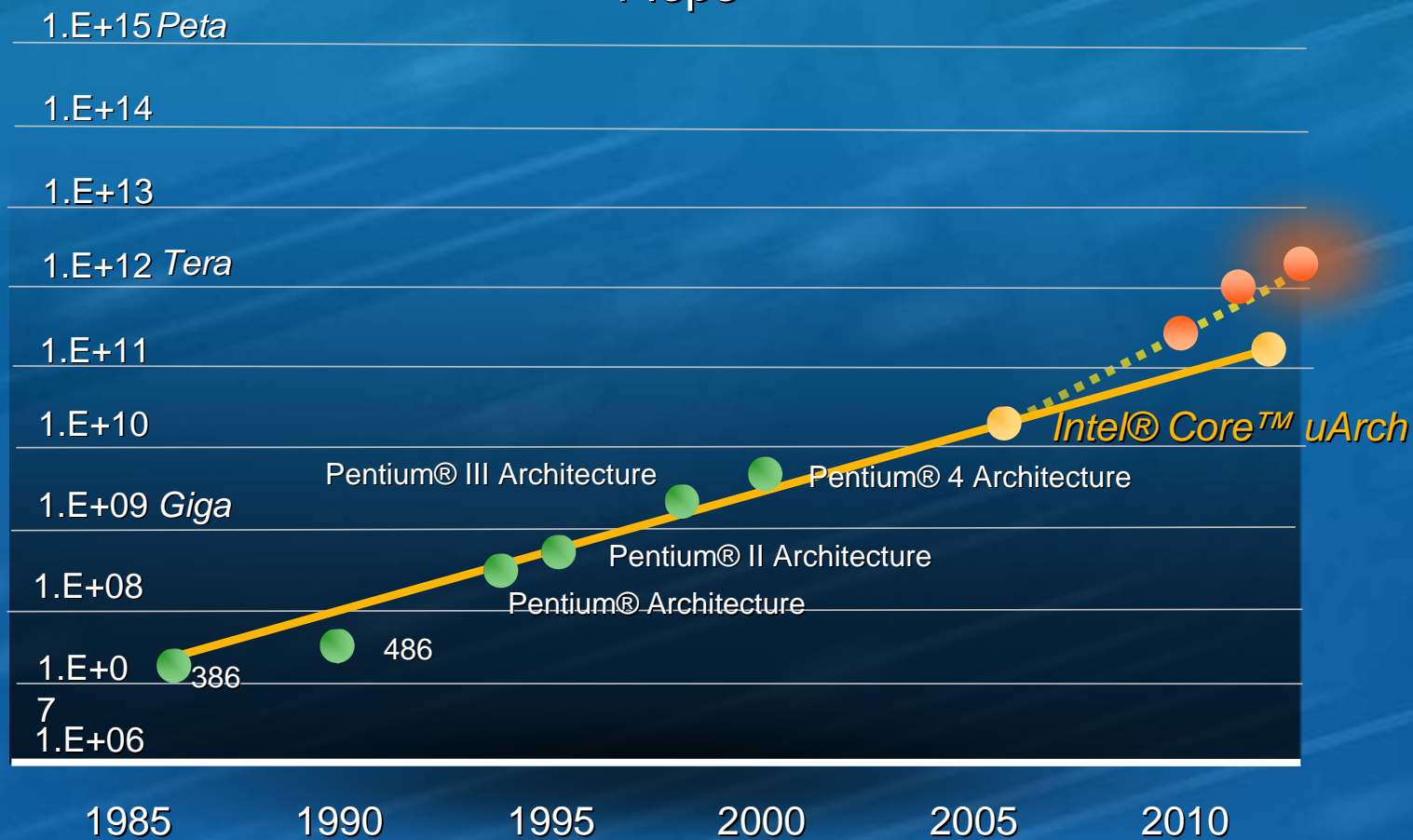
Assuming approx. 100GF processors



Increasing Processor Performance

Through Multi-threaded Cores

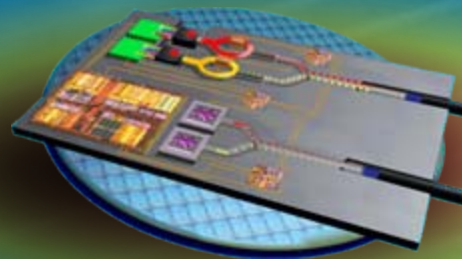
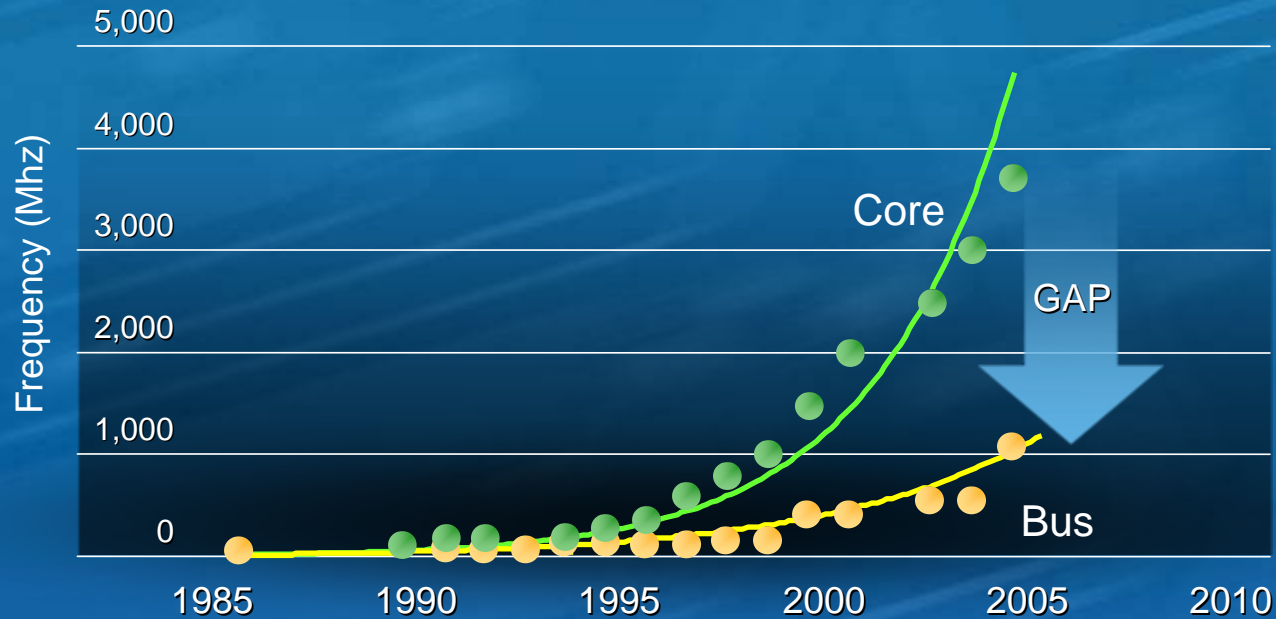
Flops



Reaching Petascale with ~1,000 Processors

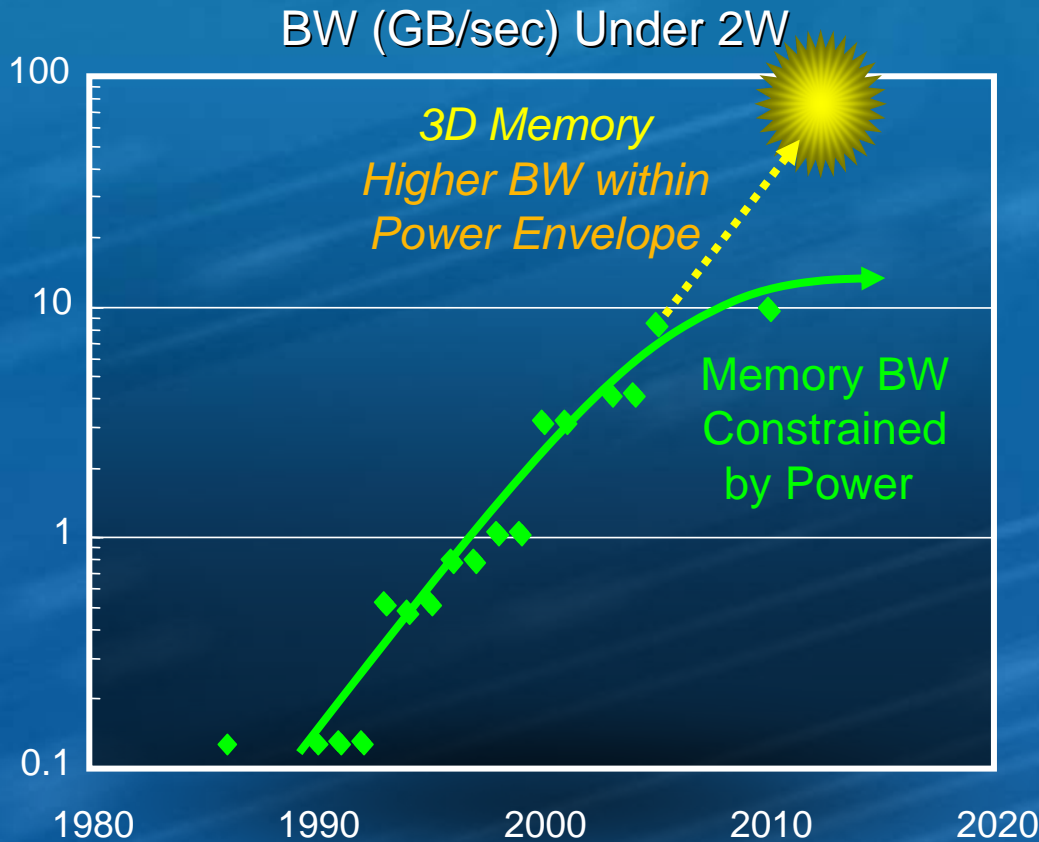


Increasing I/O Signaling Rate to Fill the Gap



Silicon Photonics

Increasing Memory Bandwidth *to Keep Pace*

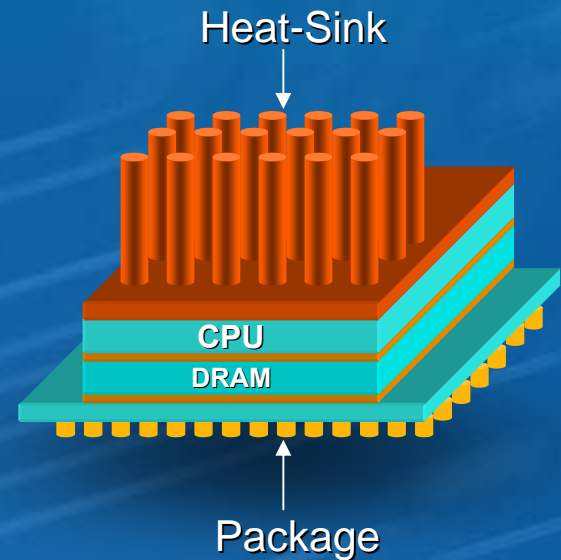


3D Memory Stacking

*Power and IO Signals Go
Through DRAM to CPU*

Thin DRAM Die

Through DRAM Vias



Source: Intel





HPC @ Intel